

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/06/2022

Details for "SN74AUP1G14DRLR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN74AUP1G14DRLR	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DRL 5	1.65x1.2x0.6	3.1

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.010911	100	1000000	0.346533	3465
Sub-Total			0.010911	100	1000000	0.346533	3465
Die Attach Adhesive							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.004624	30.002595	300026	0.146858	1469
Other Inorganic Materials	Silica	7631-86-9	0.000694	4.502985	45030	0.022041	220
Other Organic Materials	Chlorine	7782-50-5	0.000005	0.032442	324	0.000159	2
Thermoplastics	Epoxy	85954-11-6	0.010089	65.461978	654620	0.320427	3204
Sub-Total			0.015412	100	1000000	0.489485	4895
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	1.089872	97.049958	970500	34.61433	346143
Copper and Its Alloys	Iron	7439-89-6	0.029198	2.599998	26000	0.927328	9273
Copper and Its Alloys	Phosphorus	7723-14-0	0.001685	0.150044	1500	0.053516	535
Zinc and Its Alloys	Zinc	7440-66-6	0.002246	0.2	2000	0.071333	713
Sub-Total			1.123001	100	1000000	35.666507	356665
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.038434	97.296339	972963	1.220664	12207
Precious Metals	Gold	7440-57-5	0.000119	0.301251	3013	0.003779	38
Precious Metals	Palladium	7440-05-3	0.00083	2.101159	21012	0.026361	264
Precious Metals	Silver	7440-22-4	0.000119	0.301251	3013	0.003779	38
Sub-Total			0.039502	100	1000000	1.254583	12546
Mold Compound							
Other Inorganic Materials	Aluminum Nitride	24304-00-5	0.001897	0.099982	1000	0.060249	602
Other Inorganic Materials	Fused Silica	60676-86-0	1.612742	85.000024	850000	51.22068	512207
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	0.011384	0.599997	6000	0.361556	3616
Other Plastics and Rubber	Carbon Black	1333-86-4	0.003795	0.200017	2000	0.120529	1205
Other Plastics and Rubber	Silicone	218163-11-2	0.007589	0.399998	4000	0.241027	2410
Thermoplastics	Epoxy	85954-11-6	0.259936	13.7	137000	8.255566	82556
Sub-Total			1.897343	100	1000000	60.259606	602596
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.062446	100	1000000	1.983285	19833
Sub-Total			0.062446	100	1000000	1.983285	19833
Total			3.148615			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 06/06/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meets JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.